

Vishay Siliconix

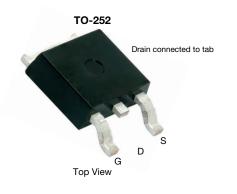
RoHS

COMPLIANT HALOGEN

FREE

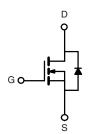
Automotive N-Channel 60 V (D-S) 175 °C MOSFET

PRODUCT SUMMARY d				
V _{DS} (V)	60			
$R_{DS(on)} (\Omega)$ at $V_{GS} = 10 V$	0.042			
$R_{DS(on)} (\Omega)$ at $V_{GS} = 4.5 V$	0.060			
I _D (A)	15			
Configuration	Single			
Package	TO-252			



FEATURES

- TrenchFET[®] power MOSFET
- 100 % R_g and UIS tested
- AEC-Q101 qualified
- Package with low thermal resistance
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>



N-Channel MOSFET

ABSOLUTE MAXIMUM RA	TINGS (T _C = 25	5 °C, unless otherwise	noted)		
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-Source Voltage		V _{DS}	60	- V	
Gate-Source Voltage		V _{GS}	V _{GS} ± 20		
Continuous Drain Current	T _C = 25 °C ^a		15		
Continuous Drain Current	T _C = 125 °C	I _D	10		
Continuous Source Current (Diode Co	ontinuous Source Current (Diode Conduction) ^a		15	А	
Pulsed Drain Current ^b		I _{DM}	50		
Single Pulse Avalanche Current	ngle Pulse Avalanche Current		18		
Single Pulse Avalanche Energy		E _{AS}	16.2	mJ	
Mauiana Daura Diasia stian b	T _C = 25 °C	D	37	W	
Maximum Power Dissipation ^b	$T_{C} = 125 \text{ °C} \qquad P_{D} \qquad 11$		~~~		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	-55 to +175	°C	

THERMAL RESISTANCE RA	TINGS			
PARAMETER		SYMBOL	LIMIT	UNIT
Junction-to-Ambient	PCB Mount ^c	R _{thJA}	50	°C (M)
Junction-to-Case (Drain)	nction-to-Case (Drain) R _{thJC} 4 °C/W		0/10	

Notes

a. Package limited.

b. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.

c. When mounted on 1" square PCB (FR4 material).



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PARAMETER	SYMBOL	TES	T CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static					1	1	1
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} =	= 0 V, I _D = 250 μΑ	60	-	-	
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} =	- V _{GS} , I _D = 250 μΑ	1.5	2	2.5	V
Gate-Source Leakage	I _{GSS}	V _{DS} =	0 V, $V_{GS} = \pm 20 V$	-	-	± 100	nA
		$V_{GS} = 0 V$	V _{DS} = 60 V	-	-	1	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{GS} = 0 V$	V _{DS} = 60 V, T _J = 125 °C	-	-	50	μA
		$V_{GS} = 0 V$	V _{DS} = 60 V, T _J = 175 °C	-	-	150	- V nA μA Α Ω
On-State Drain Current ^a	I _{D(on)}	$V_{GS} = 10 V$	$V_{DS} \ge 5 V$	30	-	-	Α
		$V_{GS} = 10 V$	I _D = 10 A	-	0.036	0.042	
		$V_{GS} = 10 V$	I _D = 10 A, T _J = 125 °C	-	-	0.075	1
Durin Courses On Otata Desistance 8		$V_{GS} = 10 V$	I _D = 10 A, T _J = 175 °C	-	-	0.090	
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 4.5 V$	I _D = 10 A, T _J = 125 °C	-	0.092	-	Ω
		$V_{GS} = 4.5 V$	I _D = 10 A, T _J = 175 °C	-	0.110	-	
		$V_{GS} = 4.5 V$	I _D = 10 A	-	0.048	0.060	
Forward Transconductance ^b	9 _{fs}	$V_{DS} = 15 \text{ V}, \text{ I}_{D} = 6 \text{ A}$		-	11	-	S
Dynamic ^b							
Input Capacitance	C _{iss}			-	425	535	
Output Capacitance	C _{oss}	$V_{GS} = 0 V$	V _{DS} = 25 V, f = 1 MHz	-	95	120	pF
Reverse Transfer Capacitance	C _{rss}			-	40	50	
Total Gate Charge ^c	Qg			-	9.5	15	
Gate-Source Charge ^c	Q _{gs}	V _{GS} = 10 V	$V_{DS} = 30 \text{ V}, I_D = 15 \text{ A}$	-	1.7	-	nC
Gate-Drain Charge ^c	Q _{gd}			-	2.5	-	
Gate Resistance	Rg	f = 1 MHz		1.2	2.5	5.4	Ω
Turn-On Delay Time ^c	t _{d(on)}			-	5	8	
Rise Time ^c	t _r	$V_{DD} = 30 \text{ V}, \text{ R}_L = 2 \Omega$ $\text{I}_D \cong 15 \text{ A}, \text{ V}_{\text{GEN}} = 10 \text{ V}, \text{ R}_g = 1 \Omega$		-	10	15	- ns
Turn-Off Delay Time ^c	t _{d(off)}			-	13	20	
Fall Time ^c	t _f			-	8	12	
Source-Drain Diode Ratings and Chara	acteristics ^b						
Pulsed Current ^a	I _{SM}			-	-	50	А
Forward Voltage	V _{SD}	I _F =	10 A, V _{GS} = 0 V	-	0.9	1.2	V
Reverse Recovery Time	t _{rr}	I _F = 15	A, dl/dt = 100 A/µs	-	29	60	ns

Notes

a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.

c. Independent of operating temperature.

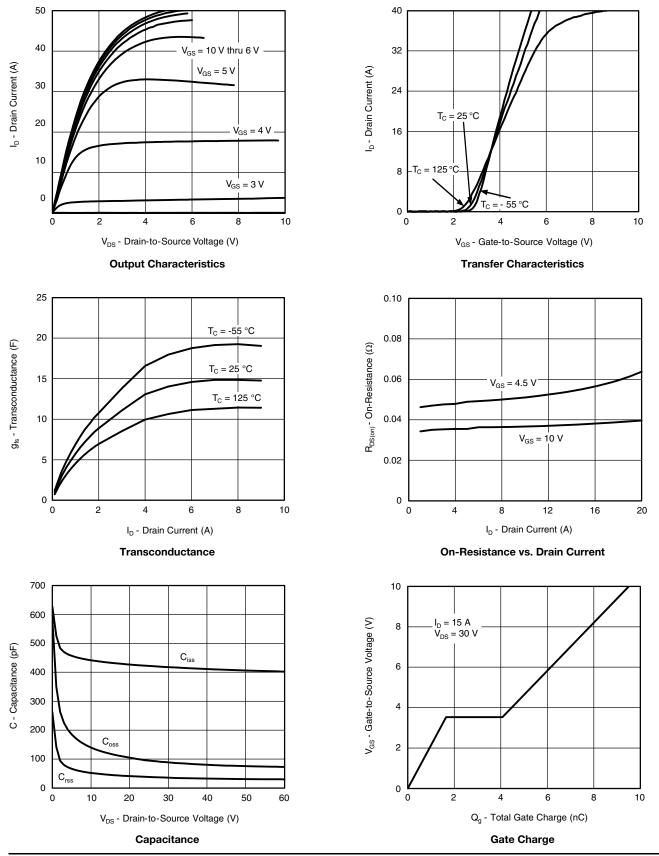
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



S15-1873-Rev. G, 10-Aug-15

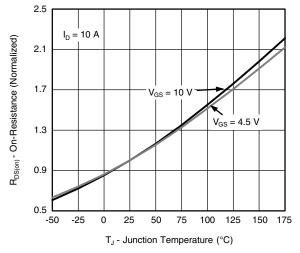
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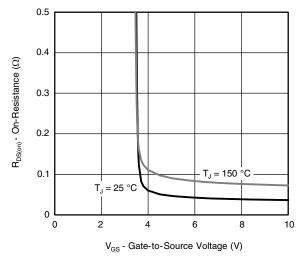
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



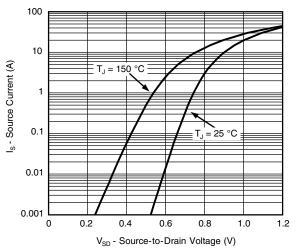
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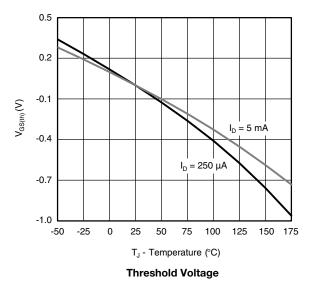
On-Resistance vs. Junction Temperature

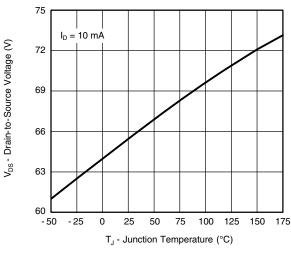


On-Resistance vs. Gate-to-Source Voltage



Source Drain Diode Forward Voltage





On-Resistance vs. Junction Temperature

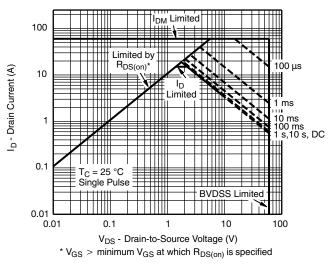
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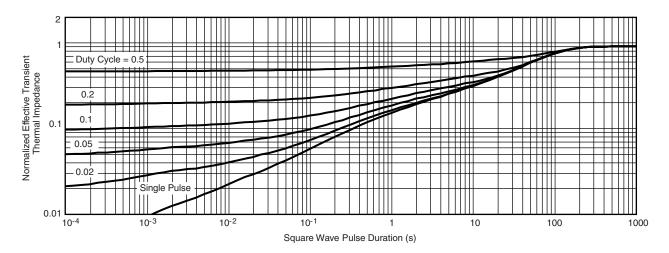


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THERMAL RATINGS ($T_A = 25 \text{ °C}$, unless otherwise noted)



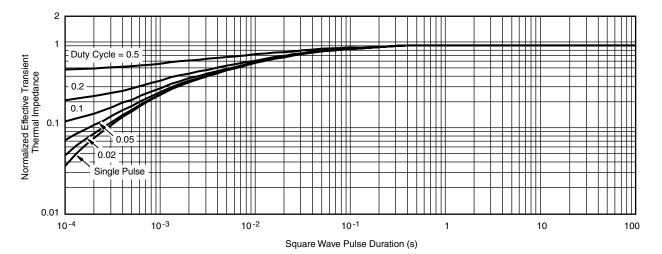
Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Ambient



THERMAL RATINGS (T_A = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Case

Note

The characteristics shown in the two graphs

- Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)

- Normalized Transient Thermal Impedance Junction-to-Case (25 °C)

are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?68880.

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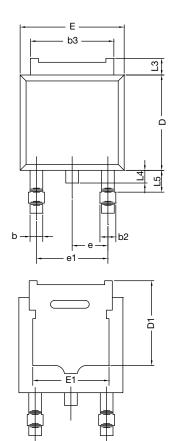
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REVISION	HISTORY ^a	
REVISION	DATE	DESCRIPTION OF CHANGE
G	04-Aug-15	Revised R _g minimum limit

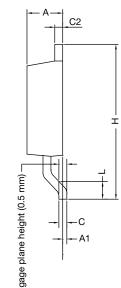
Note

a. As of April 2014





TO-252AA Case Outline

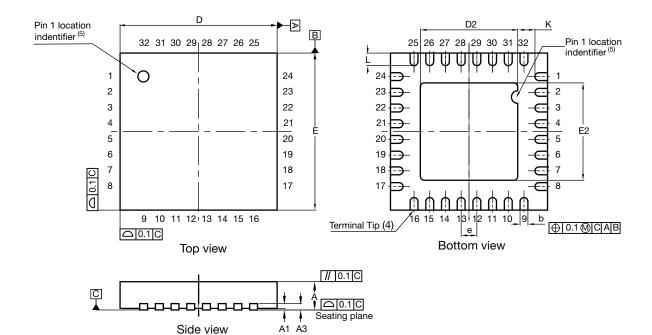


	MILLIMETERS		INC	INCHES		
DIM.	MIN.	MAX.	MIN.	MAX.		
А	2.18	2.38	0.086	0.094		
A1	-	0.127	-	0.005		
b	0.64	0.88	0.025	0.035		
b2	0.76	1.14	0.030	0.045		
b3	4.95	5.46	0.195	0.215		
С	0.46	0.61	0.018	0.024		
C2	0.46	0.89	0.018	0.035		
D	5.97	6.22	0.235	0.245		
D1	4.10	-	0.161	-		
Е	6.35	6.73	0.250	0.265		
E1	4.32	-	0.170 -			
Н	9.40	10.41	0.370	0.410		
е	2.28	2.28 BSC 0.090 BSC				
e1	4.56	BSC	0.180 BSC			
L	1.40	1.78	0.055	0.070		
L3	0.89	1.27	0.035	0.050		
L4	-	1.02	- 0.04			
L5	1.01	1.52	0.040	0.060		
ECN: T13- DWG: 601	0592-Rev. A, (9	02-Sep-13				

Note

• Dimension L3 is for reference only.





QFN32 5 x 5 Case Outline

DIM	MILLIMETERS			INCHES			
DIM.	MIN.	NOM.	MAX.	MIN.	I. NOM.		
А	0.75	0.85	0.95	0.029	0.033	0.037	
A1	0.00	-	0.05	0.000	-	0.002	
A3		0.20 ref.			0.008 ref.		
b	0.18	0.25	0.30	0.007	0.010	0.012	
D	5.00 BSC			0.197 BSC			
D2	3.00	3.10	3.20	0.118	0.122	0.126	
е	0.50 BSC				0.020 BSC		
E	5.00 BSC			0.197 BSC			
E2	3.00	3.10	3.20	0.118	0.122	0.126	
К	0.20	-	-	0.008	-	-	
L	0.30	0.40	0.50	0.012	0.016	0.020	
N ⁽³⁾	32				32		
Nd ⁽³⁾	8			8			
Ne ⁽³⁾	8				8		

Notes

- ⁽¹⁾ Use millimeters as the primary measurement
- ⁽²⁾ Dimensioning and tolerances conform to ASME Y14.5M. 1994
- (3) N is the number of terminals, Nd is the number of terminals in X-direction and Ne is the number of terminals in Y-direction.
- ⁽⁴⁾ Dimension b applies to plated terminal and is measured between 0.15 mm and 0.30 mm from terminal tip

⁽⁵⁾ The pin #1 identifier must be existed on the top surface of the package by using indentation mark or other feature of package body (6) Package warpage max. 0.05 mm

S14-2079-Rev. A, 20-Oct-14 DWG: 6027

Revision: 20-Oct-14

1 For technical questions, contact: pmostechsupport@vishay.com Document Number: 67244

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RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)



Recommended Minimum Pads Dimensions in Inches/(mm)

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